



Semiconductor Device Type: P9X-QFN-16-3x0.9mm-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				1.16	100.00%	5.37%		
	Silicon	7440-21-3	1.16		100.00%		5.37%	53704
Lead Frame				4.94	100.00%	22.87%		
	Copper	7440-50-8	4.81		97.36%		22.27%	222661
	Iron	7439-89-6	0.12		2.42%		0.55%	5537
	Lead	7439-92-1	0.00		0.01%		0.00%	24
	Phosphorus	7723-14-0	0.01		0.11%		0.02%	241
	Zinc	7440-66-6	0.01		0.11%		0.02%	241
Lead Frame Plating				0.10	100.00%	0.46%		
	Silver	7440-22-4	0.10		100.00%		0.46%	4630
Mold Compound				13.78	100.00%	63.80%		
	Epoxy Resin	Trade Secret	0.96		7.00%		4.47%	44657
	Phenolic Resins	Trade Secret	0.69		5.00%		3.19%	31898
	Silica (Fused)	60676-86-0	10.34		75.00%		47.85%	478473
	Silicon Dioxide	7631-86-9	0.96		7.00%		4.47%	44657
	Metal Hydroxide	Trade Secret	0.69		5.00%		3.19%	31898
	Carbon Black	1333-86-4	0.14		1.00%		0.64%	6380
Die Attach				0.07	100.00%	0.32%		
	Silver	7440-22-4	0.05		67.90%		0.22%	2200
	Carbocyclic Acrylate	Trade Secret	0.01		20.00%		0.06%	648
	Bismaleimide Resin	Trade Secret	0.00		5.50%		0.02%	178
	Acrylate or Acrylic	Trade Secret	0.00		5.50%		0.02%	178
	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3	0.00		0.55%		0.00%	18
	Palladium Compound	Trade Secret	0.00		0.55%		0.00%	18
Bond Wire				0.40	100.00%	1.85%		
	Gold	7440-57-5	0.40		100.00%		1.85%	18518
Plating and Anode Ball				1.15	100.00%	5.32%		
	Lead	7439-92-1	0.00		0.05%		0.00%	27
	Tin	7440-31-5	1.15		99.95%		5.32%	53214
Totals			21.60	21.60	100.00%	100.00%	100.00%	1000000

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